

Amendments to the Specification

Please amend specification as follows.

Please amend paragraph [0025], at page 5, as follows:

As shown in FIGS. 1 and 2, a polishing apparatus according to the present invention comprises a turntable 20 and a top ring unit 4 having a top ring 3 for holding a semiconductor wafer 2 to be polished and pressing the semiconductor wafer 2 against the turntable 20. The turntable 20 is coupled to a motor 21 by a vertical shaft, and rotatable about the vertical shaft. A polishing cloth 5, such as IC-1000 manufactured by Rodel, Inc., is attached to the upper surface of the turntable 20.